Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	60	V
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current (Note 6) V_{GS} = 10V	Steady State	T_A = +25°C T_A = +70°C	I_D	13.5 10.8	A
	t<10s	T_A = +25°C T_A = +70°C	I_D	18.1 14.4	A
Maximum Continuous Body Diode Forward Current (Note 6)			I_S	3	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I_{DM}	80	A
Avalanche Current, L = 1mH			I_{AS}	14.8	A
Avalanche Energy, L = 1mH			E_{AS}	98	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_D	1.3	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	93	°C/W
	t<10s		53	°C/W
Total Power Dissipation (Note 6)		P_D	1.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	73	°C/W
	t<10s		41	°C/W
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	12.7	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	60	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 48V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	1	—	3	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	5	6	mΩ	V_{GS} = 10V, I_D = 20A
		—	5.7	7.2		V_{GS} = 6V, I_D = 20A
		—	6.7	8.9		V_{GS} = 4.5V, I_D = 12.5A
Diode Forward Voltage	V_{SD}	—	0.9	1.2	V	V_{GS} = 0V, I_S = 20A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	2962	—	pF	V_{DS} = 30V, V_{GS} = 0V, f = 1MHz
Output Capacitance	C_{oss}	—	965	—		
Reverse Transfer Capacitance	C_{rss}	—	60	—		
Gate Resistance	R_g	—	0.66	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = 10V)	Q_g	—	47.1	—	nC	V_{DD} = 30V, I_D = 20A
Total Gate Charge (V_{GS} = 4.5V)	Q_g	—	23.1	—		
Gate-Source Charge	Q_{gs}	—	10.2	—		
Gate-Drain Charge	Q_{gd}	—	12.5	—		
Turn-On Delay Time	$t_{D(ON)}$	—	8.3	—	nS	V_{DD} = 30V, V_{GS} = 10V, I_D = 20A, R_g = 3.3Ω
Turn-On Rise Time	t_R	—	9.4	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	22	—		
Turn-Off Fall Time	t_F	—	8.9	—		
Body Diode Reverse Recovery Time	t_{RR}	—	40.4	—	nS	I_F = 20A, di/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q_{RR}	—	49.7	—	nC	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

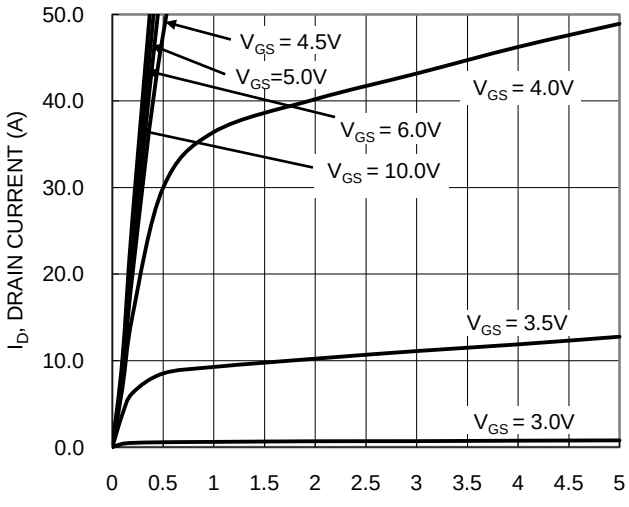


Figure 1. Typical Output Characteristic

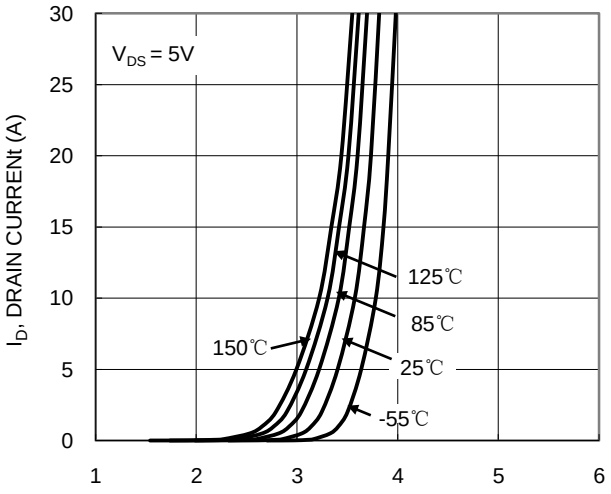


Figure 2. Typical Transfer Characteristic

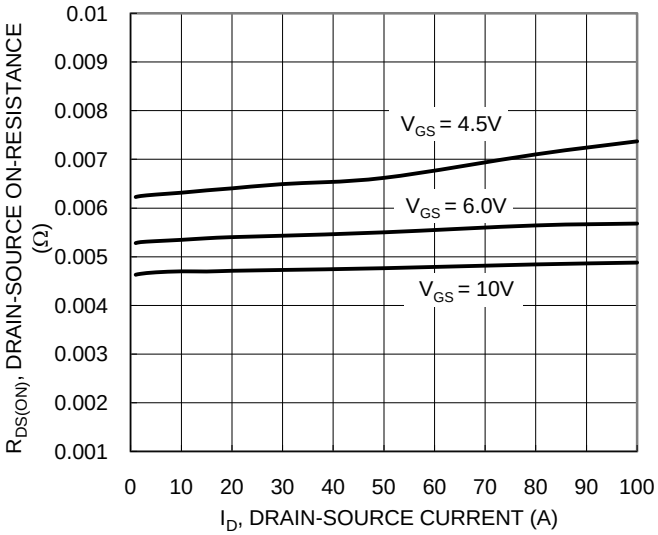


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

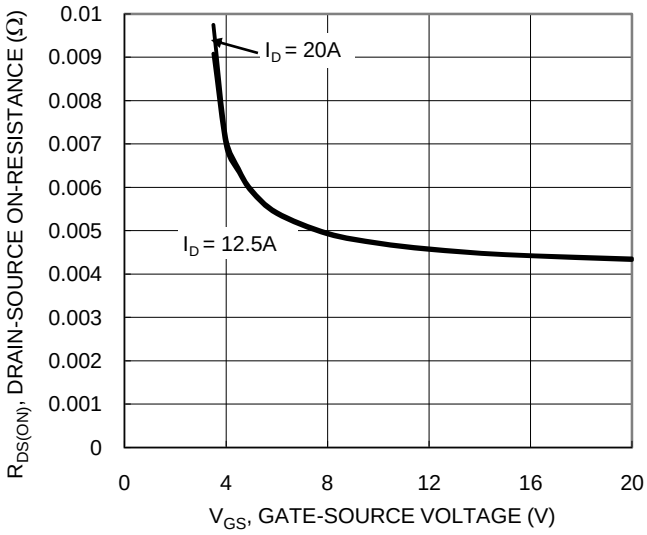


Figure 4. Typical Transfer Characteristic

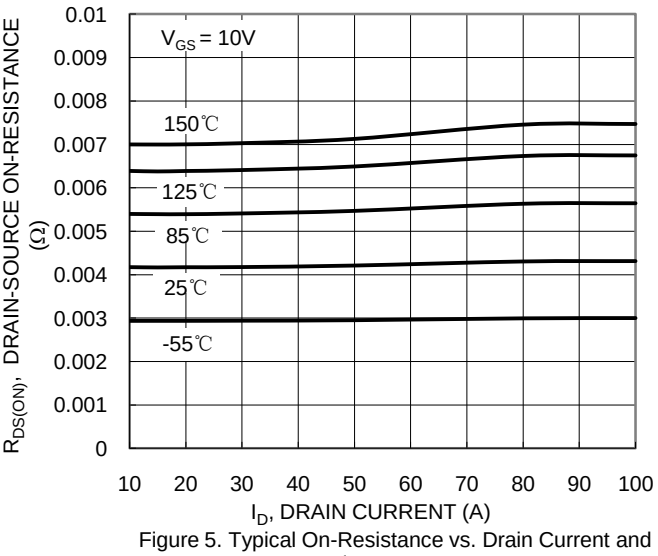


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

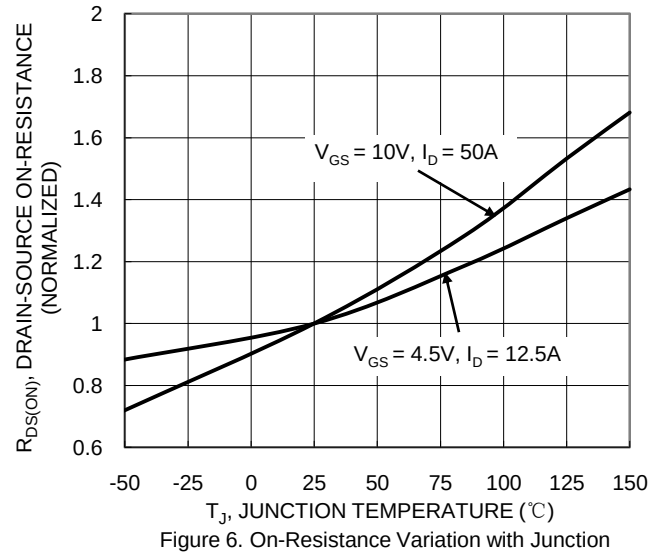


Figure 6. On-Resistance Variation with Junction Temperature

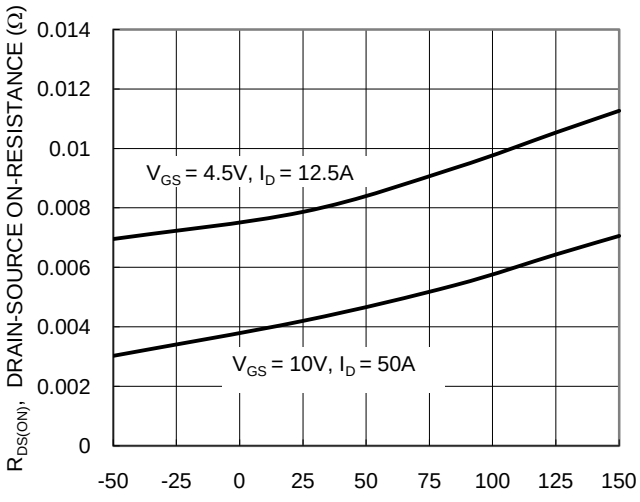


Figure 7. On-Resistance Variation with Junction Temperature

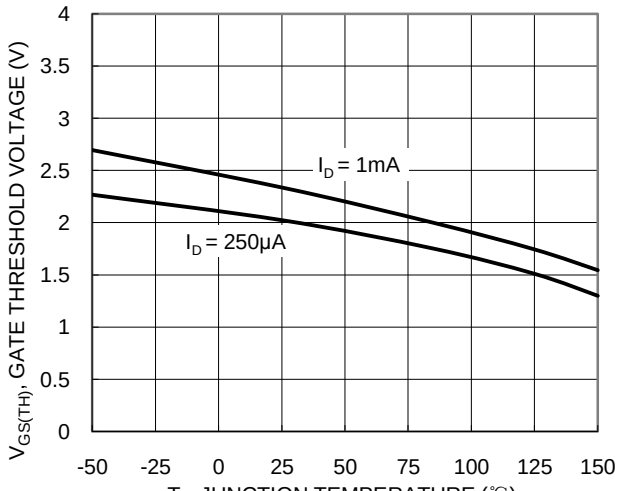


Figure 8. Gate Threshold Variation vs. Junction Temperature

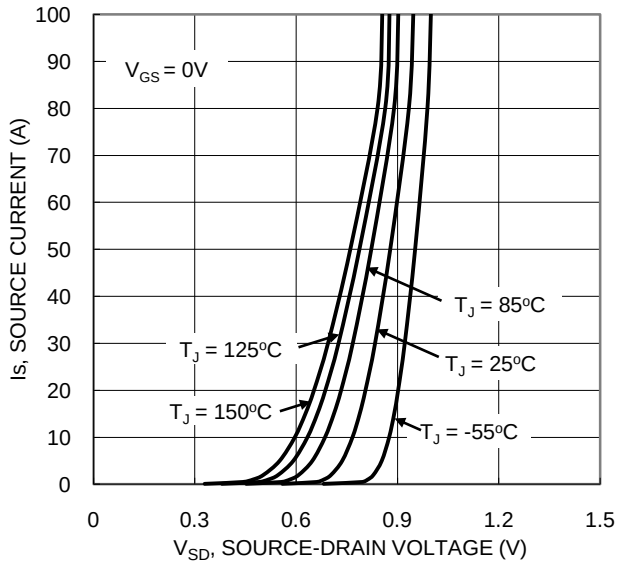


Figure 9. Diode Forward Voltage vs. Current

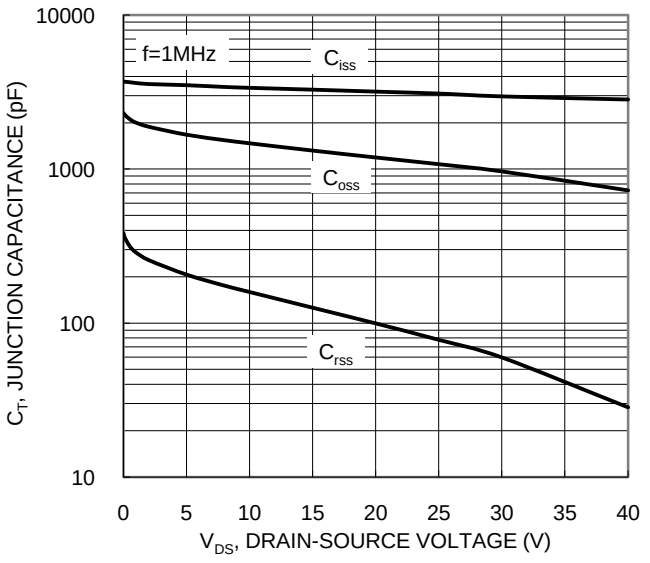


Figure 10. Typical Junction Capacitance

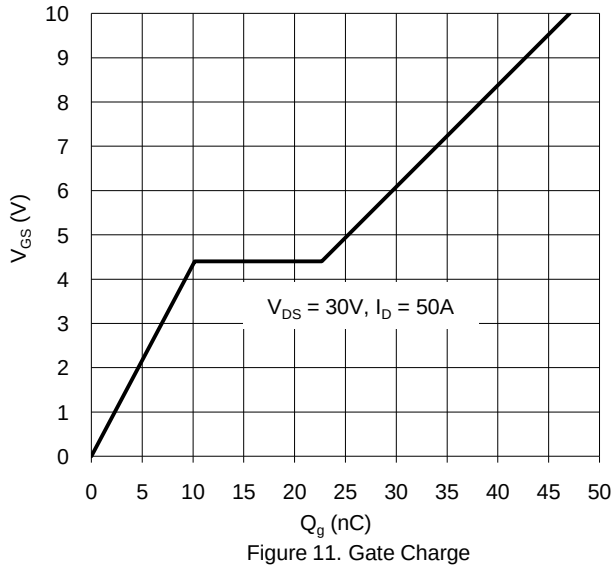


Figure 11. Gate Charge

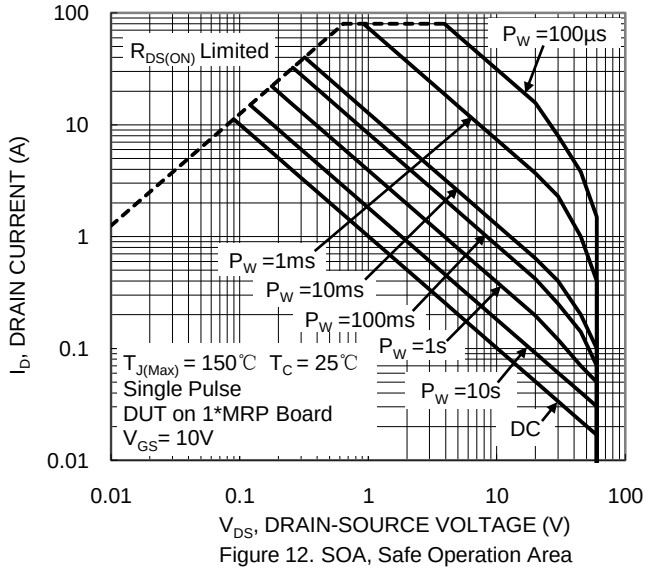


Figure 12. SOA, Safe Operation Area

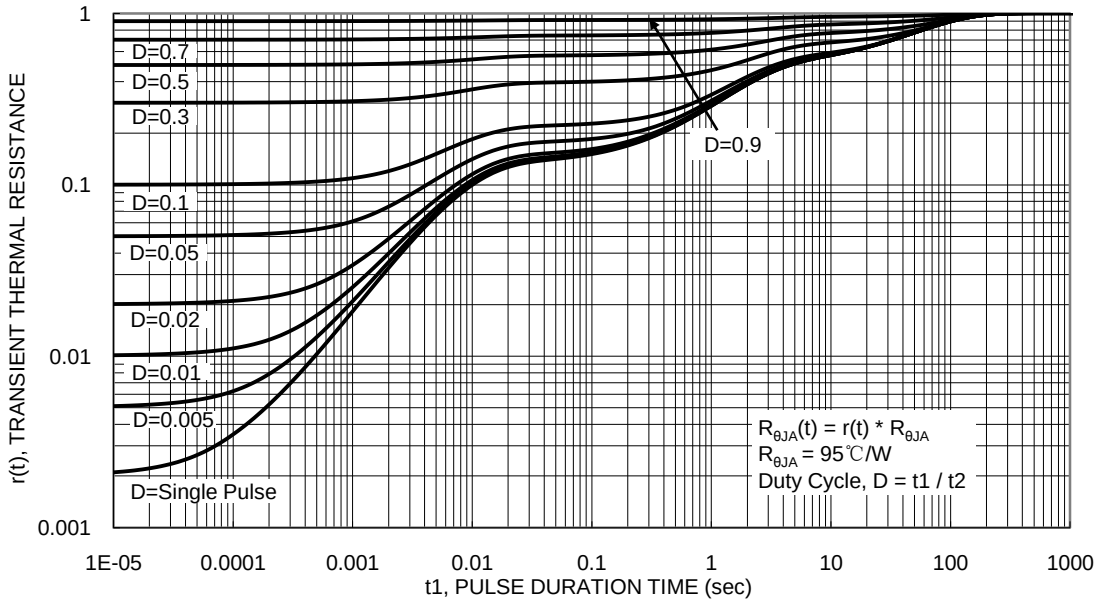
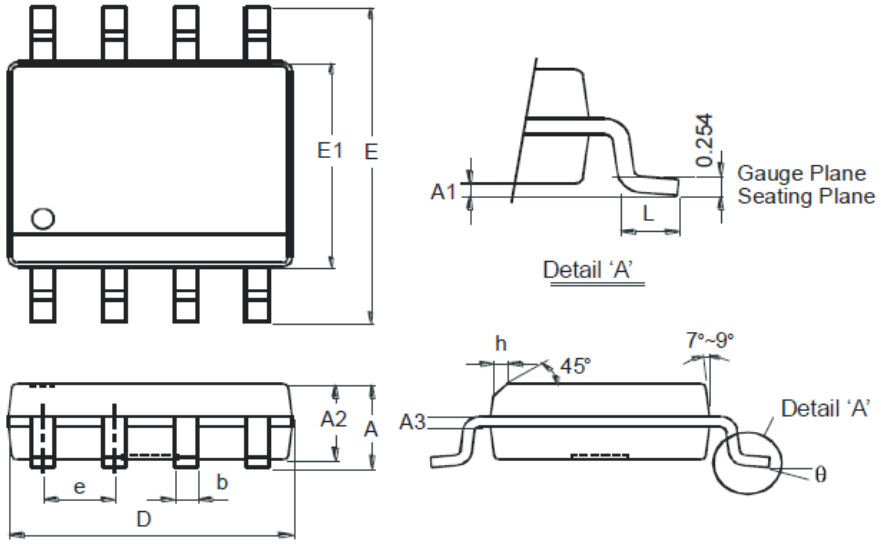


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



SO-8		
Dim	**Min**	**Max**
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout

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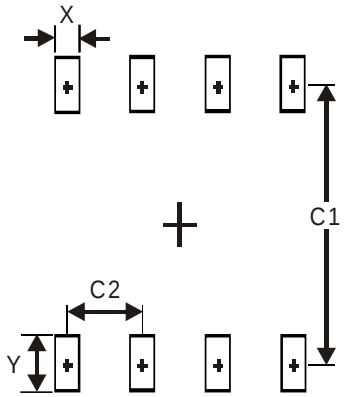
SO-8



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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